

In-House Manufacture

Excellence Guaranteed

Our engineers are there for every step of the process to ensure quality throughout. With our considerably lengthy time within the industry we have developed an extensive network with reputable companies to ensure the best in manufacture.

Initial manufacturing runs are kept in-house, however larger quantities can be outsourced offshore, keeping your unit costs to an absolute minimum while still maintaining our strict in-house quality standards.

With a recent addition of an Essemtec Paraquda to complement its existing 4 Juki 570L SMT pick and place machines, Neo has the capacity and flexibility to suit most needs. Conventional (leaded) component assembly is handled by our team of PCB assemblers, while circuit board inspection is catered for with our MIRTEC MV-2HTL AOI (Automated Optical Inspection) system - dramatically improving the accuracy and throughput over traditional manual optical systems.



Surface-Mount Assembly

Recent investment in the latest state-of-the-art Surface Mount Assembly equipment enables Neo to:

- + Place virtually any SMT component package type including large BGA's, QFP's and TSOP's.
- + BGA min ball diameter / pitch 0.2mm.
- + TSOP min lead pitch 0.3mm.
- + Place large component sizes up to 80×70mm (and 18mm high).
- + Place passive component with sizes down to 01005.
- + Work with PCB board sizes to 600×430×3.5mm.
- + Use Automated Optical Inspection (AOI) to confirm the correct assembly of each and every PCB.

Our surface mount manufacturing team are highly skilled with an attention for detail and are able to offer support & guidance on manufacturing optimisation. We also have an in-house design and engineering team to support the manufacturing at all stages of production.